

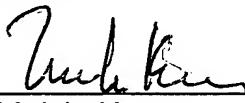
**REMARKS**

By the above amendment, the specification has been updated to indicate the patented status of the parent application. Further, claims 1 and 2 have been canceled and new claims 4-8 have been presented which recite features of the present invention as described at pages 27 and 28 of the specification and illustrated in Fig. 15, for example. As described, the damage of a wafer due to thermal shock can be suppressed by the recited features and hence the cooling efficiency can be improved.

In view of the above amendments and remarks, favorable action in this application is requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR 1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (500.41374CX2) and please credit any excess fees to such deposit account.

Respectfully submitted,



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